

### Feathers:

- Advanced trench process technology
- Ultra low  $R_{ds(on)}$ , typical 6mohm
- High avalanche energy, 100% test
- Fully characterized avalanche voltage and current

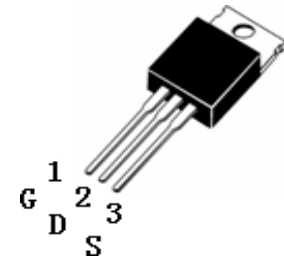
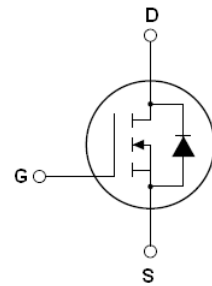
### Description:

The SSF6808 is a new generation of middle voltage and high current N-Channel enhancement mode trench power MOSFET. This new technology increases the device reliability and electrical parameter repeatability. SSF6808 is assembled in high reliability and qualified assembly house.

### Application:

- Power switching application

**ID =84A**  
**BV=68V**  
**Rdson=8mohm**



SSF6808 TOP View (TO220)

### Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D@T_c=25^\circ\text{C}$	Continuous drain current, $V_{GS}@10\text{V}$	84	A
$I_D@T_c=100^\circ\text{C}$	Continuous drain current, $V_{GS}@10\text{V}$	76	
$I_{DM}$	Pulsed drain current ①	310	
$P_D@T_c=25^\circ\text{C}$	Power dissipation	181	W
	Linear derating factor	1.5	W/°C
$V_{GS}$	Gate-to-Source voltage	$\pm 20$	V
dv/dt	Peak diode recovery voltage	31	v/ns
$E_{AS}$	Single pulse avalanche energy ②	400	mJ
$E_{AR}$	Repetitive avalanche energy	TBD	
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +175	°C

### Thermal Resistance

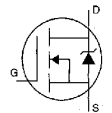
	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case	—	0.83	—	°C/W
$R_{\theta JA}$	Junction-to-ambient	—	—	62	

### Electrical Characteristics @ $T_J=25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$BV_{DSS}$	Drain-to-Source breakdown voltage	68	—	—	V	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	5	8	m $\Omega$	$V_{GS}=10\text{V}, I_D=30\text{A}$
$V_{GS(th)}$	Gate threshold voltage	2.0	—	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
$I_{DSS}$	Drain-to-Source leakage current	—	—	2	$\mu\text{A}$	$V_{DS}=68\text{V}, V_{GS}=0\text{V}$
		—	—	10		$V_{DS}=68\text{V}, V_{GS}=0\text{V}, T_J=150^\circ\text{C}$

$I_{GSS}$	Gate-to-Source forward leakage	—	—	100	nA	$V_{GS}=20V$
	Gate-to-Source reverse leakage	—	—	-100		$V_{GS}=-20V$
$Q_g$	Total gate charge	—	90	—	nC	$I_D=30A$
$Q_{gs}$	Gate-to-Source charge	—	18	—		$V_{DD}=30V$
$Q_{gd}$	Gate-to-Drain("Miller") charge	—	28	—		$V_{GS}=10V$
$t_{d(on)}$	Turn-on delay time	—	18.2	—	nS	$V_{DD}=30V$
$t_r$	Rise time	—	15.6	—		$I_D=2A, R_L=15\Omega$
$t_{d(off)}$	Turn-Off delay time	—	70.5	—		$R_G=2.5\Omega$
$t_f$	Fall time	—	13.8	—		$V_{GS}=10V$
$C_{iss}$	Input capacitance	—	3150	—	pF	$V_{GS}=0V$
$C_{oss}$	Output capacitance	—	300	—		$V_{DS}=25V$
$C_{riss}$	Reverse transfer capacitance	—	240	—		$f=1.0MHz$

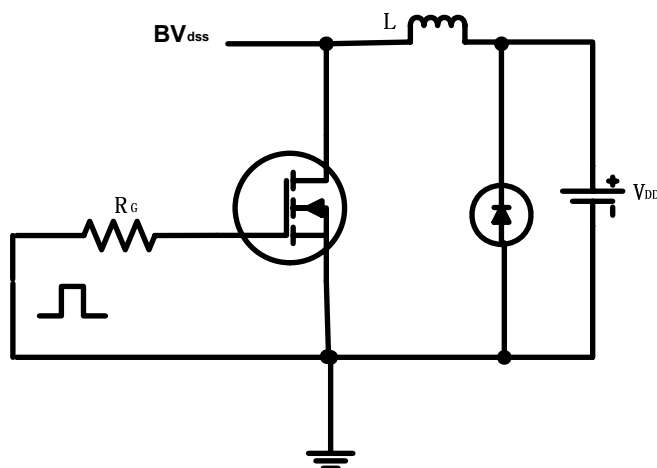
### Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	84	A	MOSFET symbol showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	310		
$V_{SD}$	Diode Forward Voltage	—	—	1.3	V	$T_J=25^\circ C, I_S=68A, V_{GS}=0V$ ③
$t_{rr}$	Reverse Recovery Time	—	57	—	nS	$T_J=25^\circ C, I_F=68A$ $di/dt=100A/\mu s$ ③
$Q_{rr}$	Reverse Recovery Charge	—	107	—	nC	
$t_{on}$	Forward Turn-on Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$ )				

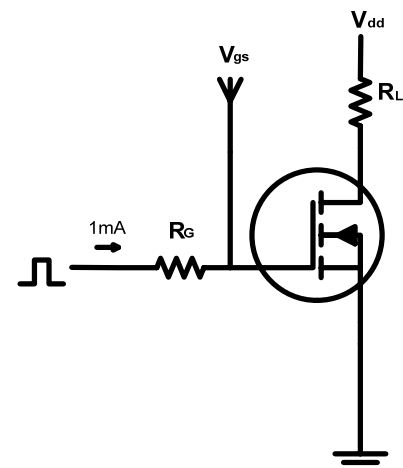
#### Notes:

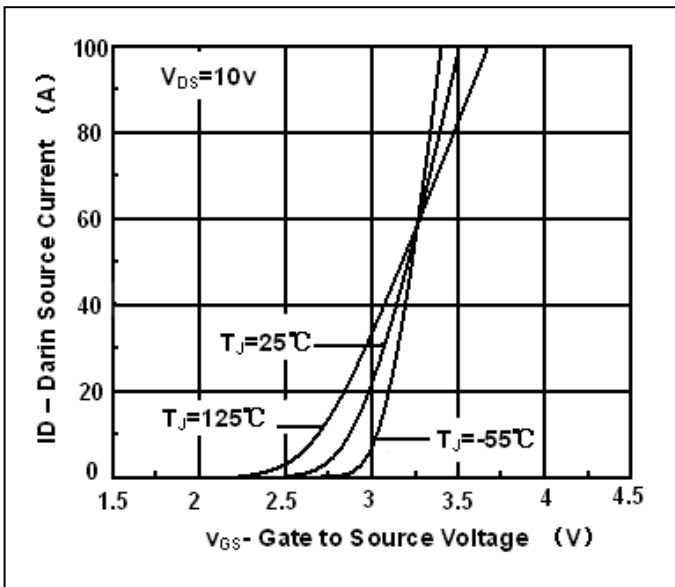
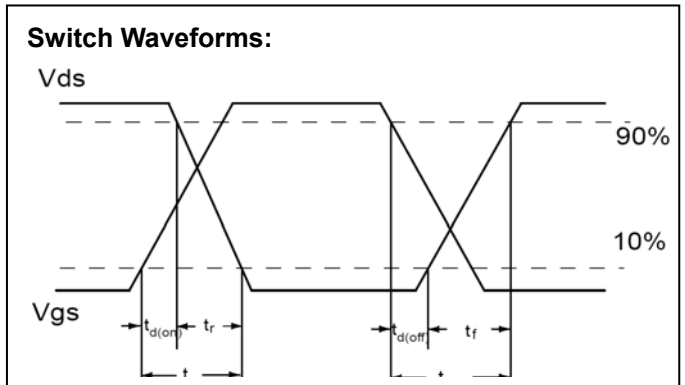
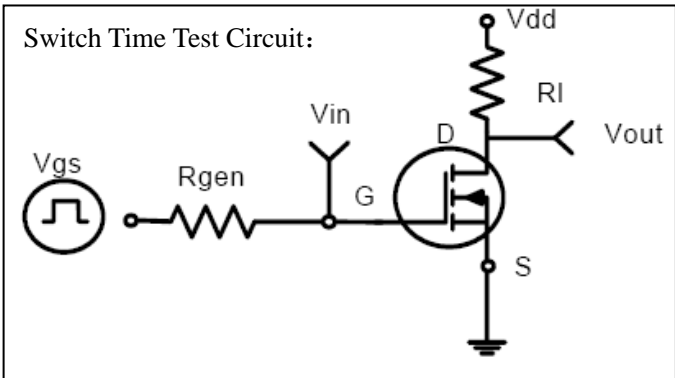
- ① Repetitive rating; pulse width limited by max junction temperature.
- ② Test condition:  $L = 0.3mH, I_D = 37A, V_{DD} = 30V$
- ③ Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 1.5\%$ ;  $R_G = 25\Omega$  Starting  $T_J = 25^\circ C$

#### EAS test circuit:

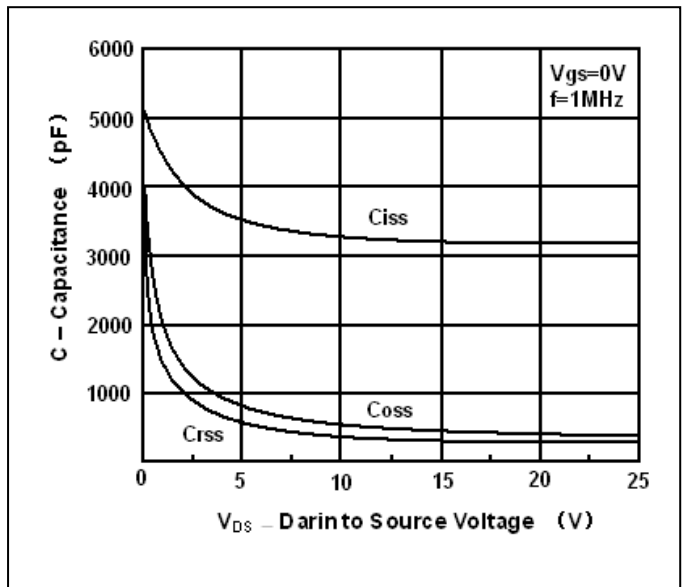


#### Gate charge test circuit:

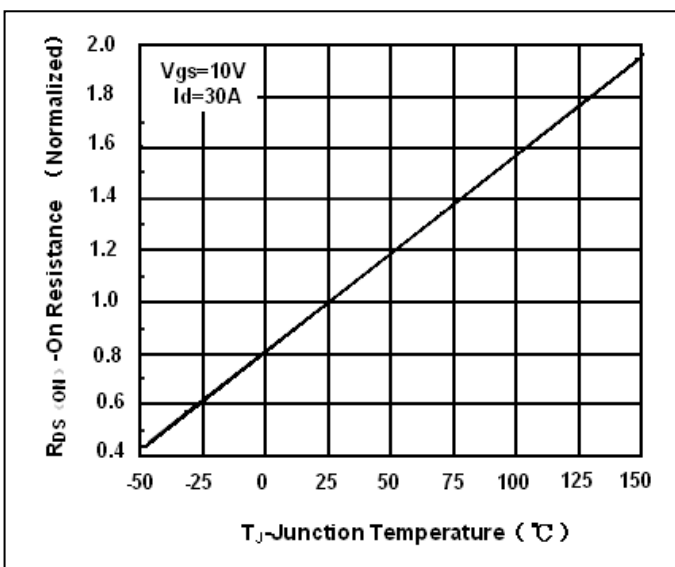




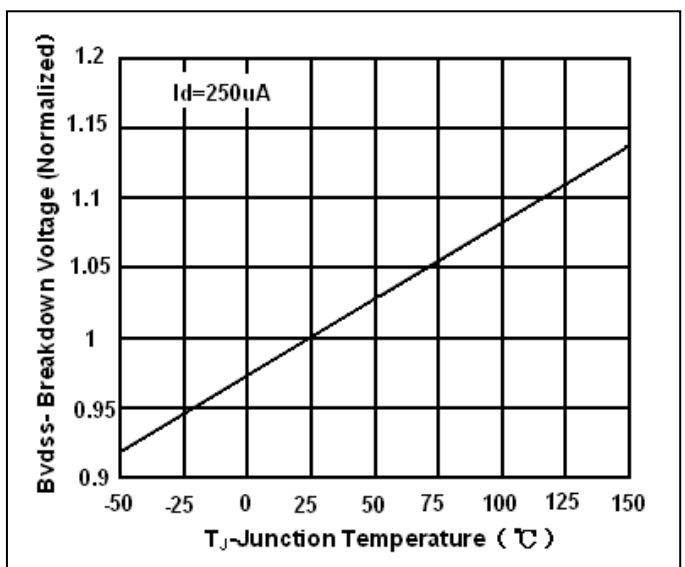
Transfer Characteristic



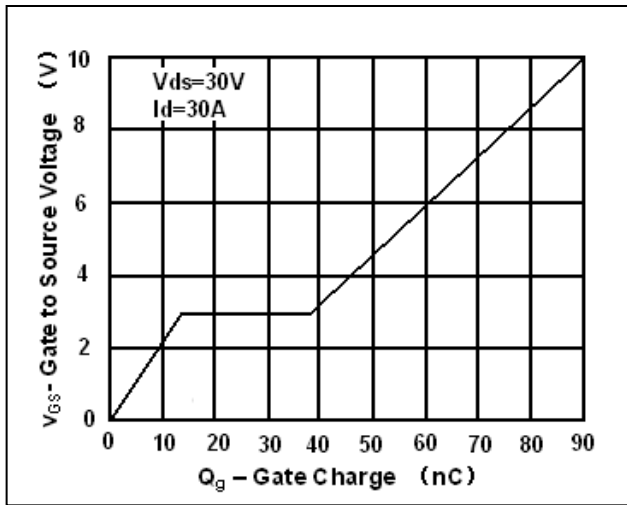
Capacitance



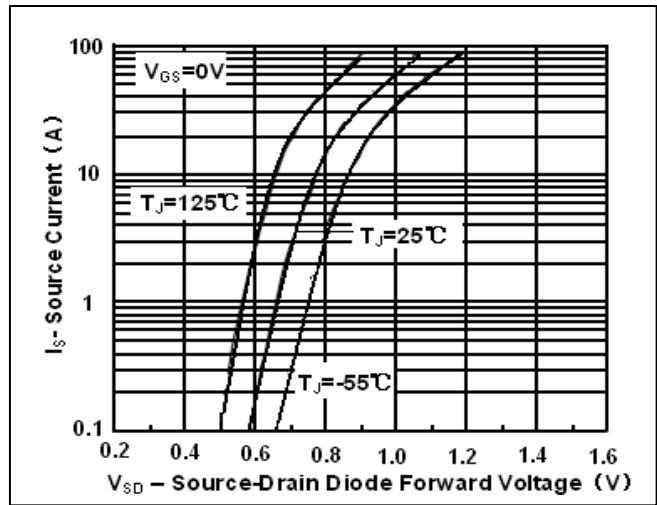
On Resistance vs. Junction Temperature



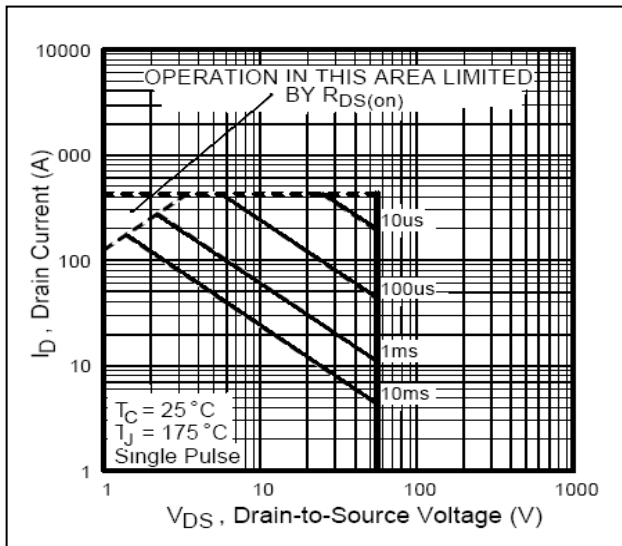
Breakdown Voltage vs. Junction Temperature



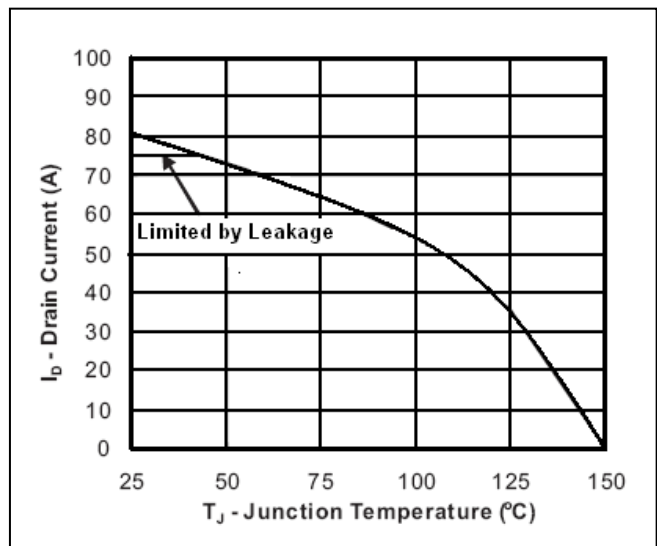
Gate Charge



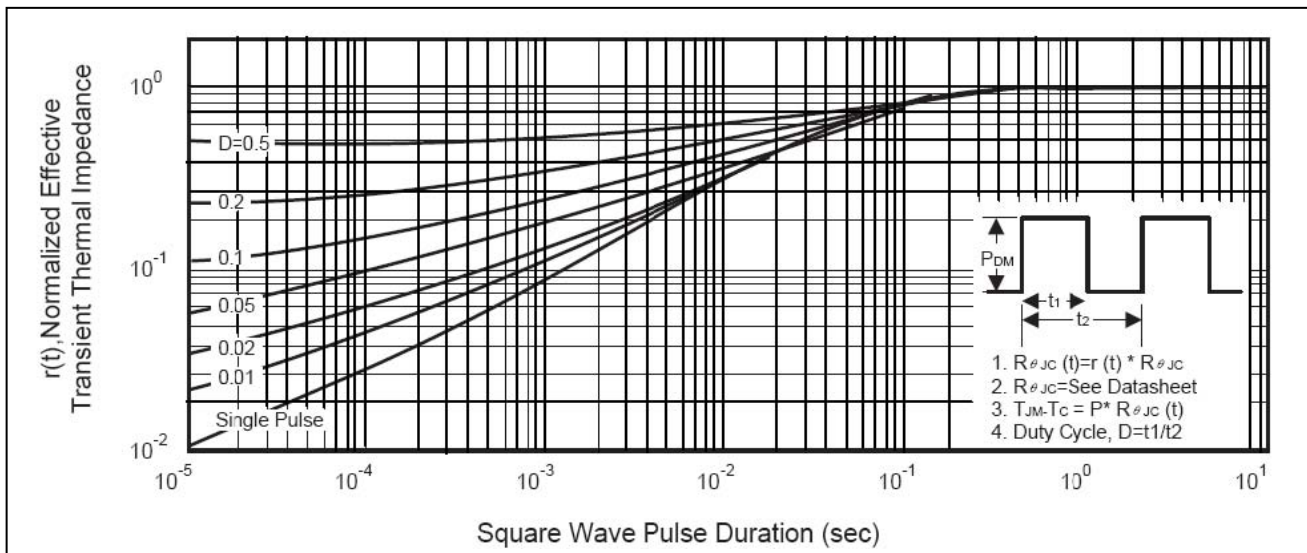
Source-Drain Diode Forward Voltage



Safe Operation Area



Max Drain Current vs. Junction Temperature



Transient Thermal Impedance Curve

## Mechanical Data:

